



## Material Content Data Sheet



Halogen-Free

Sales Product Name	BSC040N08NS5	Issued	27. April 2022
MA#	MA005726042		
Package	PG-TDSON-8-46	Weight*	118.83 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.096	0.92	0.92	9224	9224
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	iron	7439-89-6	0.038	0.03		318	
	non noble metal	copper	7440-50-8	37.762	31.78	31.82	317770	318183
wire	noble metal	gold	7440-57-5	0.045	0.04	0.04	383	383
encapsulation	organic material	carbon black	1333-86-4	0.086	0.07		724	
	plastics	epoxy resin	-	6.801	5.72		57228	
	inorganic material	silicondioxide	60676-86-0	36.155	30.42	36.21	304249	362201
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12216	12216
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1393	1393
solder	non noble metal	tin	7440-31-5	0.031	0.03		264	
	noble metal	silver	7440-22-4	0.039	0.03		330	
	non noble metal	lead	7439-92-1	1.496	1.26	1.32	12591	13185
heat sink clip	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	iron	7439-89-6	0.022	0.02		188	
	non noble metal	copper	7440-50-8	22.292	18.76	18.79	187587	187831
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			29	
	non noble metal	iron	7439-89-6	0.011	0.01		95	
	non noble metal	copper	7440-50-8	11.320	9.53	9.54	95260	95384
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

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2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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